Surface Mount > Automotive High Temperature SMD Series

Automotive High Temperature SMD Series





Applications

- Automotive and Industrial Transportation
- Infotainment/Telematics
- Climate Control Systems
- Body Electronics
- Sensor Protection
- ADAS (Advanced Driver Assistance)
- Auto Lighting
- Security and Communication Systems

Additional Information







Samples

Description

This Automotive High Temperature SMD is the first miniature high temperature PPTC series from Littelfuse with AEC-Q200 qualification for automotive applications and it provides surface mount overcurrent protection for applications where space is a prime concern and resettable protection is desired.

Features

- Meets applicable automotive industry standards
- · Compatible with high volume electronics assembly
- Smaller footprint
- High operating temperature -40°C~125°C
- Resettable solution against overcurrent and short circuit
- AEC-Q200 qualified
- RoHS compliant, halogen-free, and lead-free
- Surface-mount form factor

Benefits

- Expertise from the world's leading resettable overcurrent protection manufacturer
- Provides wider range of form factors to enhance design flexibility
- Meets ever-increasing demand for compact and space saving designs due to more electronics content in vehicle
- Restores system operation after reset when fault condition is removed, thus provides safety and protection
- Able to meet most stringent requirements for the extreme harsh automotive environment
- Suitable for standard PCB assembly to enable automated mass production

Electrical Characteristics

Part	Size	I _H	I _T	V _{MAX}	I _{MAX}	P _{D Typ}	Max Tim	e-to-trip	R _{MIN}	R _{1MAX}
Number	3126	(A)	(A)	(V _{DC})	(A)	(W)	(A)	(s)	(Ω)	(Ω)
			Automo	tive High Tem	perature SM	D – 16-30V				
picoASMDCH010F	0805	0.10	0.60	16	40	1.00	2.50	1.50	1.00	10.00
nanoASMDCH016F	1206	0.16	0.80	30	20	0.90	8.00	0.10	0.70	6.00
nanoASMDCH035F	1206	0.35	0.95	16	50	1.00	3.50	0.20	0.20	1.60
nanoASMDCH35F/30	1206	0.35	1.75	30	20	1.20	8.00	0.10	0.40	2.20
nanoASMDCH50F/24	1206	0.50	2.50	24	20	1.70	8.00	0.10	0.20	1.60

: Hold current: maximum current device will pass without interruption in 25°C, unless otherwise specified.

: Trip current: minimum current that will switch the device from low-resistance to high-resistance in 25°C still air, unless otherwise specified.

V_{MAX}: Maximum voltage device can withstand without damage at rated current.

: Maximum fault current device can withstand without damage at rated voltage

P_D: Power dissipated from device when in the tripped state in 25°C still air, unless otherwise specified.

R_{MM}: Minimum resistance of device as supplied at 25°C, unless otherwise specified.

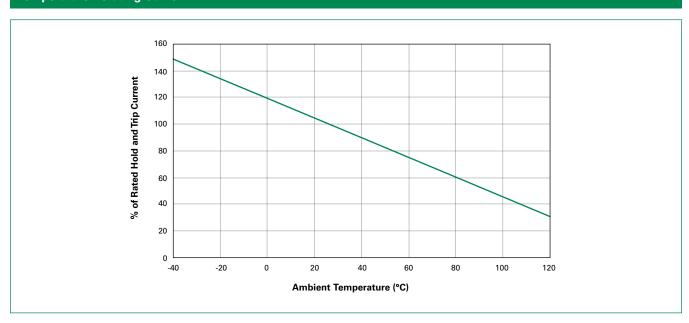
R_{IMAX}: Maximum resistance of device when measured one hour post reflow at 25°C unless otherwise specified.

* Electrical characteristics determined at 25°C.

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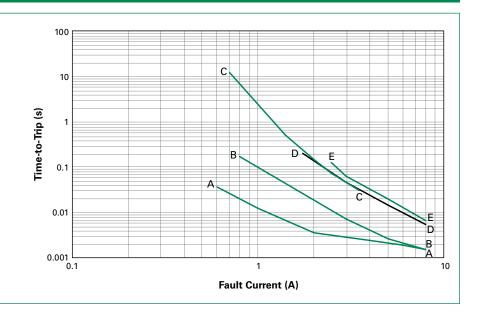
Temperature Rera	ating										
				Maximum	Ambient Te	mperature					
Part Number	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	85°C	125°C
	Hold Current (A)										
			Auto	motive Higl	n Temperatu	re SMD – 16	5-30V				
picoASMDCH010F	0.150	0.130	0.115	0.103	0.100	0.090	0.084	0.078	0.072	0.063	0.040
nanoASMDCH016F	0.250	0.210	0.190	0.170	0.160	0.140	0.130	0.120	0.110	0.090	0.050
nanoASMDCH035F	0.540	0.480	0.430	0.370	0.350	0.320	0.290	0.260	0.240	0.200	0.100
nanoASMDCH35F/30	0.510	0.460	0.410	0.360	0.350	0.310	0.290	0.260	0.240	0.200	0.100
nanoASMDCH50F/24	0.730	0.660	0.580	0.500	0.500	0.450	0.420	0.390	0.350	0.310	0.170

Temperature Rerating Curve



Typical Time-to-Trip Curves at 25°C





Physical Specifications

T . ID IM I	ACCOUNT TO STATE THE PROPERTY OF THE PROPERTY
Terminal Pad Material	100% Matte Tin with Nickel Underplate
Soldering Characteristics	Solderability per ANSI-J-STD-002 Category 3
Solder Heat Withstand	per IEC-STD 68-2-20, Test Tb, Section 5, Method 1a
Flammability Resistance	per IEC 695-2-2 Needle Flame Test for 20 seconds
Recommended Storage Conditions	40°C max, 70% RH max; Devices May Not Meet Specified Ratings if Storage Conditions are Exceeded
Operation Temperature	-40°C~125°C

Note: See PS400 for other physical specifications.

Environmental Specifications

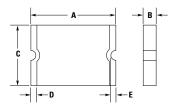
Test	Conditions	Resistance Change			
Passive Aging	60°C, 1000 hrs, 85°C, 1000 hrs	±3% Typical, ±5% Typical			
Humidity Aging 85°C, 85% R.H., 100 hrs		±1.2% Typical			
Thermal Shock	125°C, -40°C 10 times	-33% Typical			
Solvent Resistance	Freon Trichloroethane Hydrocarbons	No change No change No change			

Note: See PS400 for other environmental specifications.

Moisture Resistance Level	Level 2a, J-STD-020
Storage Conditions	40°C max, 70% RH max; devices should remain in original sealed bags prior to use. Devices may not meet specified values if these storage conditions are exceeded.

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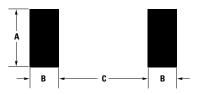
Dimensions



Dimensions

				Dime	ensions in Mi	llimeters (Inc	ches)				
Part Number	Α		E	В		С		D		E	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
			Automo	tive High Tem	perature SM	D – 16-30V					
mine A CM D CU 1010F	2.00	2.20	0.40	0.80	1.30	1.50	0.25	0.75	0.076	_	
picoASMDCH010F	(0.079)	(0.087)	(0.016)	(0.310)	(0.051)	(0.059)	(0.010)	(0.030)	(0.003)		
nanoASMDCH016F	3.00	3.40	0.61	0.89	1.37	1.80	0.25	0.75	0.076	_	
nanoASIVIDCHUTOF	(0.118)	(0.134)	(0.024)	(0.035)	(0.054)	(0.071)	(0.010)	(0.030)	(0.003)		
nanoASMDCH035F	3.00	3.40	0.91	1.14	1.37	1.80	0.25	0.75	0.076	_	
HalloASIVIDCHUSSF	(0.118)	(0.134)	(0.036)	(0.045)	(0.054)	(0.071)	(0.010)	(0.030)	(0.003)		
nanoASMDCH35F/30	3.00	3.40	1.16	1.46	1.37	1.80	0.25	0.75	0.076	_	
nanoASIVIDCH35F/30	(0.118)	(0.134)	(0.046)	(0.057)	(0.054)	(0.071)	(0.010)	(0.030)	(0.003)		
nono A SMAD CHEOE/24	3.00	3.40	1.16	1.46	1.37	1.80	0.25	0.75	0.076		
nanoASMDCH50F/24	(0.118)	(0.134)	(0.046)	(0.057)	(0.054)	(0.071)	(0.010)	(0.030)	(0.003)	_	

Recommended Pad Layout

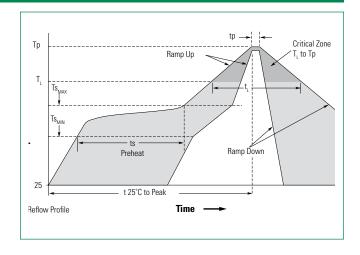


Packaging and Marking Information

Part	Tape and Reel	Tape and Reel Standard Part		Recomn	Agency			
Number	Quantity	Package	Marking	Dimension A (Nom)	Dimension B (Nom)	Dimension C (Nom)	Recognition	
		Autom	otive High Temper	ature SMD - 16-30	V			
picoASMDCH010F	4,000	20,000	L	1.50 (0.060)	1.00 (0.039)	1.20 (0.047)	_	
nanoASMDCH016F	3,000	15,000	H16	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	_	
nanoASMDCH035F	3,000	15,000	H35	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	_	
nanoASMDCH35F/30	3,000	15,000	V	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	_	
nanoASMDCH50F/24	3,000	15,000	H50	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	_	

Solder Reflow Recommendations

Profile Feature	Pb-Free Assembly
Average ramp up rate (Ts _{MAX} to Tp)	3°C/s max
Preheat	
• Temperature min (Ts _{MIN})	150°C
• Temperature max (Ts _{MAX})	200°C
• Time (ts _{MIN} to ts _{MAX})	60-120 s
Time maintained above:	
• Temperature (T _L)	217°C
• Time (t _L)	60-150 s
Peak/Classification temperature (Tp)	260°C
Time within 5°C of actual peak temperature	
Time (tp)	30 s max
Ramp down rate	3°C/s max
Time 25°C to peak temperature	8 min max



Note: All temperatures refer to topside of the package, measured on the package body surface.

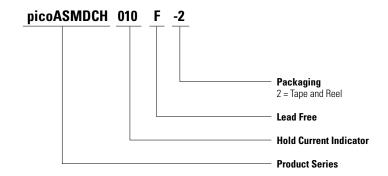
Solder Reflow

- · Recommended reflow method: IR, hot air, nitrogen.
- Recommended maximum paste thickness: 0.25mm (0.010in)
- Devices can be cleaned using standard methods and aqueous solvents.
- Experience has shown the optimum conditions for forming acceptable solder fillets occur when a reasonable amount of solder paste is placed underneath each device's termination. As such, we request that customers comply with our recommended solder pad layouts.
- Customer should validate that the solder paste amount and reflow recommendations meet its application.
- We request that customer board layouts refrain from placing raised features (e.g. vias, nomenclature, traces, etc.) underneath PolySwitch devices. It is possible that raised features could negatively impact solderability performance of our devices.

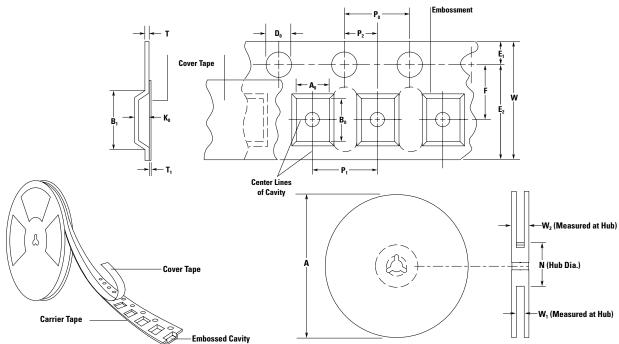
Rework

• Standard industry practices. (Please also avoid direct contact to the device.)

Part Ordering Number System



Tape and Reel Diagrams



Warning:

- Users should independently evaluate the suitability of and test each product selected for their own application.
- Operation beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- These devices are intended for protection against damage caused by occasional overcurrent or overtemperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Contamination of the PPTC material with certain silicone-based oils or some aggressive solvents can adversely impact the performance of the devices.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components
- PPTC devices are not recommended for installation in applications where the device is constrained such that its PTC properties are inhibited, for example in rigid potting materials or in rigid housings, which lack adequate clearance to accommendate device expansion.
- Operation in circuits with a large inductance can generate a circuit voltage (Ldi/dt) above the rated voltage of the device.

Tape and Reel Specifications

	EIA 481-1								
Description	picoASMDCH010F	nanoASMDCH016F nanoASMDCH035F	nanoASMDCH035F/30 nanoASMDCH050F/24						
W	8.0 ± 0.30	8.0 ± 0.30	8.0 ± 0.30						
P _o	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10						
P ₁	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10						
P ₂	2.0 ± 0.10	2.0 ± 0.05	2.0 ± 0.05						
A ₀	1.70 ± 0.1	1.95 ± 0.1	1.95 ± 0.1						
B _o	2.45 ± 0.1	3.5 ± 0.1	3.5 ± 0.1						
B ₁ max	4.35	4.35	4.35						
D _o	1.55 ± .05	1.55 ± .05	1.55 ± .05						
F	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05						
E ₁	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10						
E ₂ min	6.25	6.25	6.25						
T max	0.3	0.6	0.6						
T ₁ max	0.1	0.1	0.1						
K _o	0.86 ± 0.1	1.27 ± 0.1	1.50 ± 0.1						
A max	185	185	185						
N min	50	50	50						
W ₁	8.4 + 1.5/00	8.4 + 1.5/00	8.4 + 1.5/00						
W₂ max	14.4	14.4	14.4						

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